Preliminary Product Information Sheet

EPO-TEK® OE145-6 (*formerly 120-38-4*)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date:	September 2017		
Rev:	V		
No. of Components:	Two		
Mix Ratio by Weight:	100 : 33		
Specific Gravity:	Part A: 1.20	Part B: 0.90	
Pot Life:	< 2 Hours		
Shelf Life- Bulk:	One year at room temperature		

Recommended Cure: 65°C / 3 Hours

Minimum Alternative Cure(s):
May not achieve performance properties listed below
80°C / 1 Hour
23°C / 24 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- *TOTAL MASS SHOULD NOT EXCEED 25 GRAMS*

Product Description: A slightly thixotropic version of EPO-TEK® 302-3M designed to meet European regulatory requirements. It is a a two component epoxy used for optical, fiber optic, and semiconductor applications. The epoxy is good for adhesive joining, sealing, potting, or as a coating. It is an enhanced adhesion version of EPO-TEK® OE145-4 with superior 85°C/85% RH resistance.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	**Cure condition:** varies as required		
Color (before cure):	Part A: Clear, slight yellow	Part B: Clear yellow	
Consistency:	Pourable liquid		
Viscosity (23°C) @ 100 rpm:	708	cPs	
Thixotropic Index:	2.0		
Glass Transition Temp:	63	°C	(Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -40-200°C @20°C/Min)
Shore D Hardness:	78		
Die Shear @ 23°C:	27	Kg	
Degradation Temp:	363	°C	
Weight Loss:			
@ 200°C:	0.07	%	
@ 250°C:	0.40	%	
@ 300°C:	1.42	%	
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Particle Size:	≤ 20	microns	

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	≥ 96% @ 560 - 1660	nm
Refractive Index:	1.5396 @ 589	nm

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com